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IN THE CLAIMS:

Please substitute the following claims for the previous claims:

- (Currently Amended) A plasma resistant <u>substrate processing</u> <u>chamber</u> component capable of being exposed to a plasma in a process chamber, the component comprising:
 - (a) a substrate processing chamber component structure; and
- (b) an electroplated coating on the <u>substrate processing</u>
 chamber component structure, the electroplated coating comprising yttrium-containing species.
- (Original) A component according to claim 1 wherein the yttriumcontaining species comprises one or more of elemental yttrium and yttrium oxide.
- (Original) A component according to claim 1 wherein the yttriumcontaining species comprises yttrium oxide, and wherein the electroplated coating further comprises aluminum oxide or zirconium oxide.
- 4. (Currently Amended) A component according to claim 3 wherein the electroplated coating comprises a compound comprising a-stoichiometric ratio of yttrium oxide and aluminum oxide.
- 5. (Original) A component according to claim 3 wherein the electroplated coating comprises partially stabilized zirconium oxide.
- 6. (Original) A component according to claim 1 wherein the electroplated coating comprises a thickness having a gradually changing concentration of the yttrium-containing species therethrough.

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7. (Currently Amended) A process substrate processing chamber comprising:

- (a) a wall around a process zone;
- (b) a substrate support in the process zone;
- (c) a ring about the substrate;
- (d) a gas distributor;
- (e) a gas energizer; and
- (f) a gas exhaust port,

wherein at least one of the wall, substrate support, ring, or gas distributor, comprises a plasma-resistant component capable of being exposed to a plasma in a process chamber, the component comprising a structure having an electroplated coating comprising yttrium-containing species; and

whereby a substrate transported into the process chamber can be processed by a gas released by the gas <u>distributor</u> supply, energized by the gas energizer, and exhausted by the gas exhaust <u>port</u>.

- 8. (Currently Amended) A somponent chamber according to claim 7 wherein the yttrium-containing species comprises one or more of elemental yttrium and yttrium oxide.
- 9. (Currently Amended) A component chamber according to claim 7 wherein the yttrium-containing species comprises yttrium oxide, and wherein the electroplated coating further comprises aluminum oxide or zirconium oxide.
- 10. (Currently Amended) A component chamber according to claim 7 wherein the electroplated coating comprises a compound comprising a steichiometric ratio of yttrium oxide and aluminum oxide.
- 11. (Currently Amended) A component chamber according to claim 7 wherein the electroplated coating comprises partially stabilized zirconium oxide.

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12. (Currently Amended) A component chamber according to claim 7 wherein the electroplated coating comprises a thickness having a gradually changing concentration of the yttrium-containing species therethrough.

13 - 22. (Cancelled)

- 23. (New) A component according to claim 1 wherein the electroplated coating comprises a thickness having a concentration gradient of yttrium therethrough.
- 24. (New) A component according to claim 1 wherein the electroplated coating comprises a thickness having a concentration gradient of aluminum therethrough.
- 25. (New) A component according to claim 1 wherein the electroplated coating is fabricated by annealing a first electroplated layer comprising aluminum or zirconium, and a second electroplated layer comprising yttrium.
- 26. (New) A component according to claim 25 comprising annealing the layers to form oxidized species.
- 27. (New) A component according to claim 1 wherein the electroplated coating is fabricated by electroplating a layer comprising a mixture of (i) yttrium and (ii) aluminum or zirconium onto the surface, and annealing the layer.